GR 97 P 1861D

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant   : Volker Weinreich et al.

Applic. No.   : 09/645,807

Filed   : August 24, 2000

Title   : Method of Producing an Electrode Configuration
                  and Method of Electrically Contacting the
                  Electrode Configuration

Examiner   : Shamim Ahmed

Group Art Unit : 1746

D E C L A R A T I O N under 37 C.F.R. § 1.132

The undersigned Dr. Manfred Engelhardt herby declares:

I have nineteen years experience in the technical field of
etching. Before this time I got the title PhD. Now I work as a
project leader for a researcher group at Infineon Technologies
AG, Germany, Munich. I have by now over 100 publication. About
50 percent of these publications are invited publication.

I declare that a person skilled in the art would have known at
the time of filing how to form a first conductive layer of
material which is substantially unetchable by chemical dry-
etching as described and disclosed in the above-identified
application without undue experimentation. This is also
clearly shown and described in the articles:

"Challenges in plasma etching and patterning for fabrication of new systems and devices, M. Engelhardt et al.,
Journal of Vacuum Science & Technology A, Second Series, Volume 17, Number 4, Part I, July/August 1999, pp 1536 - 1538.

"Impact of Chemistry and Process Kit Characteristics on Etch Rate Non-Uniformities in Pattern Transfer", M. Engelhardt
Proc. Thin Film Processing Symp.
The Electrochem. Soc. Proc. Vol. 2001-24, 42 (2001)

The undersigned declares that all statements made herein of his own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and such wilful false statements may jeopardize the validity of the application or any patent issued thereon.

Munich, April, 11, 2003

[Name of the signatory]   [Place, Date]